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Part Number:

0736565000

Status:

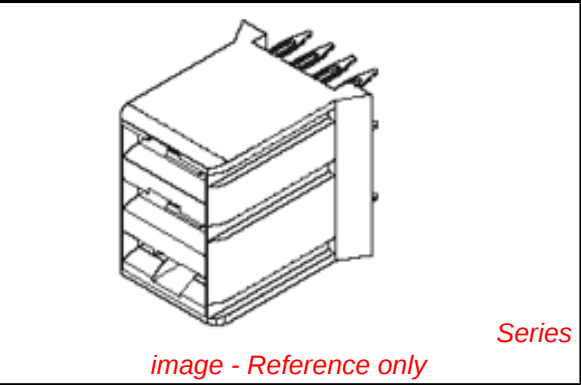
Active

Overview:

[hdm](#)

Description:

2.00mm (.079") Pitch HDM® Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 3 Circuits



Documents:

[3D Model](#)

[RoHS Certificate of Compliance \(PDF\)](#)

[Product Specification PS-73670-9999 \(PDF\)](#)

General	
Product Family	Backplane Connectors
Series	73656
Application	Backplane
Comments	Midplane Power Module, Molex Series 73659
Component Type	Power Header
Overview	hdm
Product Name	HDM®
Style	N/A
Physical	
Circuits (Loaded)	3
Circuits (maximum)	3
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Beryllium Copper
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Number of Columns	1
Number of Pairs	Open Pin Field
Number of Rows	3
Orientation	Vertical
PC Tail Length (in)	0.138 In
PC Tail Length (mm)	3.50 mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness Recommended (in)	0.098 In
PCB Thickness Recommended (mm)	2.50 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.000 In
Pitch - Mating Interface (mm)	0.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	2
Plating min: Termination (µm)	0.05
Polarized to PCB	Yes
Stackable	No
Surface Mount Compatible (SMC)	No
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

Electrical

EU RoHS

RoHS Compliant by Exemption

REACH SVHC

Contains SVHC: No

Halogen-Free

Status

Not Reviewed

China RoHS



Pb

Need more information on product environmental compliance?

Email productcompliance@molex.com

For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

73656Series

Mates With

[73651](#) HDM® Board-to-Board Daughterboard Power Module

Current - Maximum per Contact	15A
Data Rate	1.0 Gbps
Shielded	No
Voltage - Maximum	500V AC

Material Info

Reference - Drawing Numbers

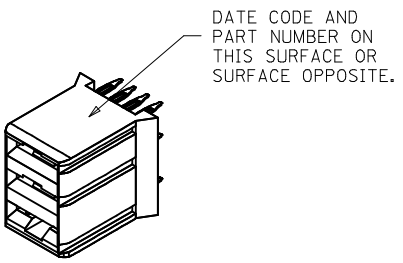
Application Specification	AS-73656-1998
Packaging Specification	PK-70873-0819
Product Specification	PS-73670-9999
Sales Drawing	SDA-73656-*00*

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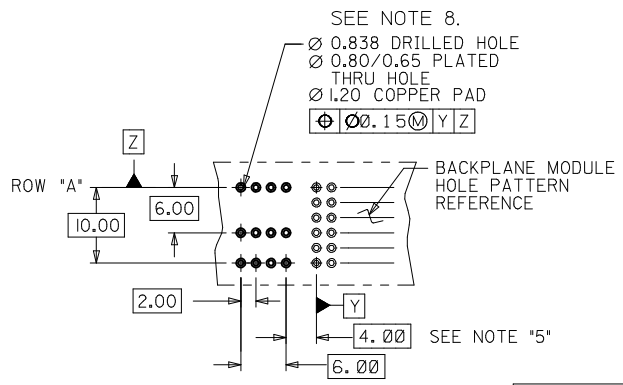
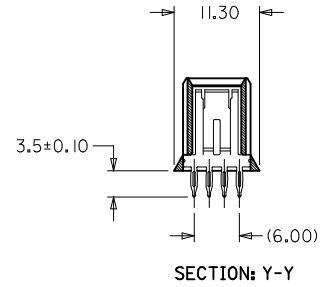
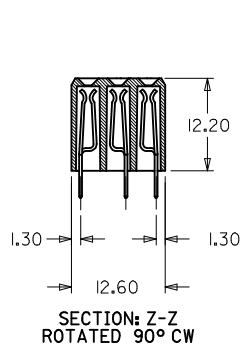
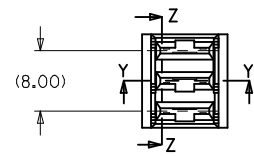
This document was generated on 05/14/2010

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ASSEMBLY NUMBER	FINISH
73656-0000	SEE NOTE 2.
73656-0001	SEE NOTE 3.



DATE CODE AND
PART NUMBER ON
THIS SURFACE OR
SURFACE OPPOSITE.



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

- NOTES:
1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK
TERMINAL - COPPER ALLOY
 2. FINISH: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.76 micrometer MINIMUM THICKNESS: NICKEL (Ni) AND GOLD FLASH OVERALL
 3. FINISH: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.76 micrometer MINIMUM THICKNESS: TIN/LEAD (Sn/Pb) OVER NICKEL (Ni) IN COMPLIANT AREA: NICKEL (Ni) OVERALL ON REMAINING WITH SELECTIVE GOLD (Au) FLASH.
 4. THIS DIMENSION MUST BE A MULTIPLE OF 4.00 mm.
 5. DIMENSIONS ARE IN MILLIMETERS.
 6. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
 7. PACKAGE ASSEMBLIES PER PK-70873-0819.
 8. HOLE SIZE SPECIFICATION IS FOR TIN/LEAD PLATED HOLES ONLY. FOR OTHER PLATING TYPES SEE MOLEX APPLICATION AS-73670-9996.
 9. THIS PART CONFORMS TO MOLEX COSMETIC SPECIFICATION PS-45499-002 CLASS B.

F

E

D

C

B

A

F

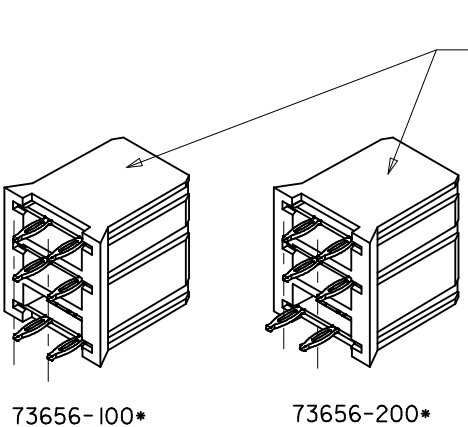
E

D

C

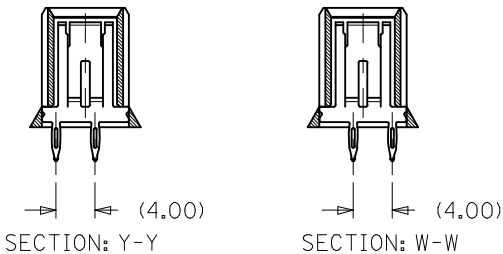
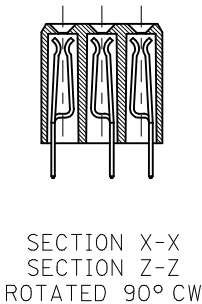
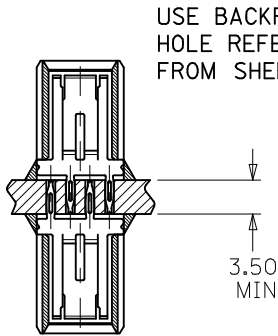
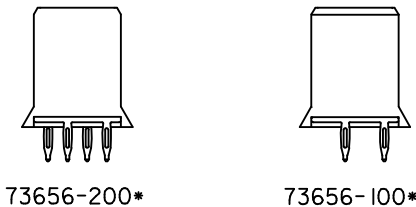
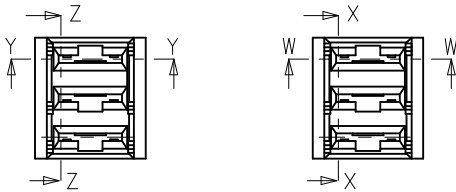
B

A



MIDPLANE OPTION

ASSEMBLY NUMBER	FINISH (SEE SHT 1)
73656-1000	SEE NOTE 2. (GOLD TAILS)
73656-2000	
73656-1001	SEE NOTE 3. (TIN/LEAD TAILS)
73656-2001	



QUALITY SYMBOLS				GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
						MM ONLY		1:1	METRIC		
						DRAWN BY		DATE		TITLE	
						ELO		1998/05/21		SALES ASSY , HDM	
						CHECKED BY		DATE		BACKPLANE POWER MODULE	
						SMR		1998/05/21		(PRESSFIT)	
						APPROVED BY		DATE		MOLEX INCORPORATED	
						CAB		1998/05/21		MATERIAL NO.	
						SEE TABLE		DOCUMENT NO.		SDA-73656-*00*	
						SIZE B		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SHEET NO.	
										2 OF 4	

ASSEMBLY NUMBER

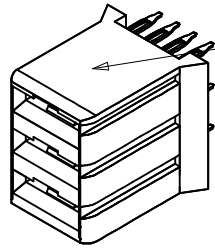
FINISH (SHT I)

73656-5000

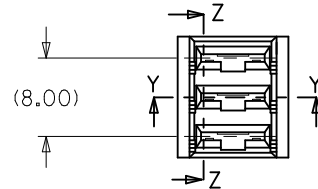
SEE NOTE 2.

73656-5001

SEE NOTE 3.



DATE CODE AND
PART NUMBER ON
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SURFACE OPPOSITE.



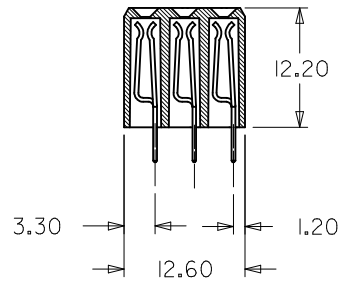
(8.00)

11.30

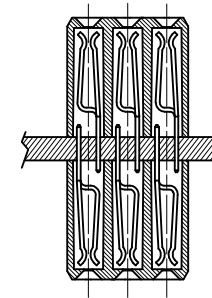
3.5±0.10

(6.00)

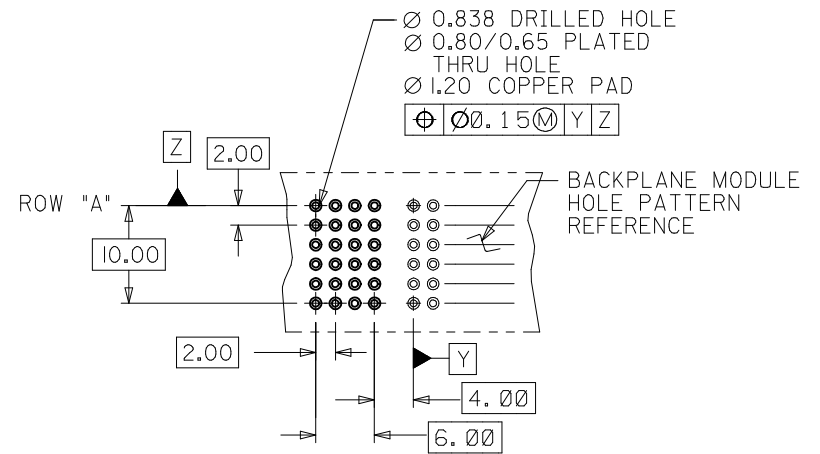
SECTION: Y-Y



SECTION: Z-Z
ROTATED 90° CW



2.36 MIN



Ø 0.838 DRILLED HOLE
Ø 0.80/0.65 PLATED
THRU HOLE
Ø 1.20 COPPER PAD

⌀ Ø0.15 (M) Y Z

BACKPLANE MODULE
HOLE PATTERN
REFERENCE

GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		mm	INCH	DRAWN BY	DATE	TITLE	
4 PLACES	± ---	± ---	± ---	ELO	1998/05/21	SALES ASSY, HDM BACKPLANE POWER MODULE (PRESSFIT) MOLEX INCORPORATED	
3 PLACES	± ---	± ---	± ---	CHECKED BY	DATE		
2 PLACES	± ---	± ---	± ---	SMR	1998/05/21		
1 PLACE	± ---	± ---	± ---	APPROVED BY	DATE		
ANGULAR ±1/2°				CAB	1998/05/21		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		MATERIAL NO.		DOCUMENT NO.	SHEET NO.
		SIZE B		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SDA-73656-*00*	3 OF 4

ASSEMBLY NUMBER

FINISH

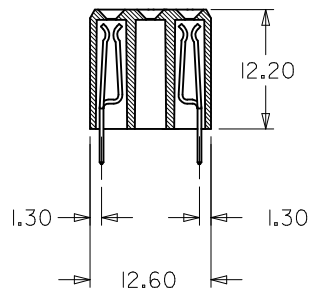
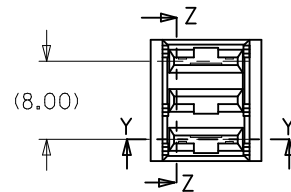
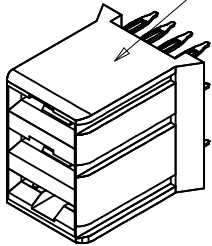
73656-0180

SEE NOTE 2.

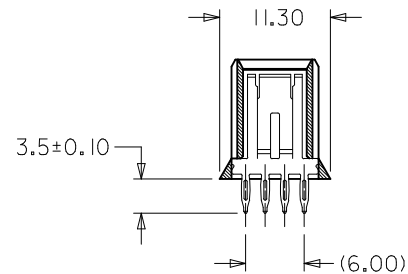
73656-0181

SEE NOTE 3.

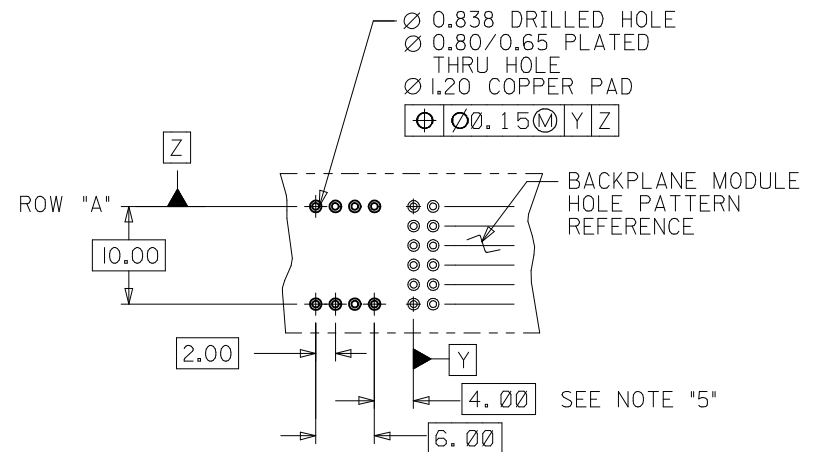
DATE CODE AND
PART NUMBER ON
THIS SURFACE OR
SURFACE OPPOSITE.



SECTION: Z-Z
ROTATED 90° CW



SECTION: Y-Y



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

SEE SHEET 1 EC NO: UCP2009-1813 DRWN:SDANIELLEY 2009/07/17 CHKD:SMART 2009/07/24 APPR:SMILLER 2009/07/24	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE		SCALE	DESIGN UNITS	 THIRD ANGLE PROJECTION	
			MM ONLY		1:1	METRIC		
			DRAWN BY DATE		TITLE			
			ELO 1998/05/21					
			CHECKED BY DATE		SALES ASSY , HDM BACKPLANE POWER MODULE (PRESSFIT)			
			SMR 1998/05/21					
			APPROVED BY DATE		MOLEX INCORPORATED			
			CAB 1998/05/21					
			MATERIAL NO.		DOCUMENT NO.			SHEET NO. 4 OF 4
			SEE TABLE		SDA-73656-*00*			
REV	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
		SIZE B						

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- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
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- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

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Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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